

your partner for soldering solutions



NIHON SUPERIOR

For Immediate Release

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SN100C Provides Faster Wetting and Increased Spreadability Over SAC305 – Visit Booth #1G08 at NEPCON South China

OSAKA, JAPAN — August 2017 — Nihon Superior Co. Ltd., an advanced joining material supplier, announces its Nihon Superior Shanghai subsidiary will exhibit in Booth #1G08 at NEPCON South China, scheduled to take place August 29-31, 2017 at the Shenzhen Convention & Exhibition Center. The reliability of SN100C has been proven in a wide range of electronics assembly products. The eutectic character of the silver-free SN100C alloy and the associated high fluidity provides faster wetting and increased spreadability over SAC305.

During the show, the company will showcase products that offer solutions for some of the challenges the electronics industry is now facing, such as improvements in reliability, thermally stable joining, and lead-free die attach.

SN100CV™ P506 D4 is a lead-free, no-clean solder paste with its basic composition of (Sn-Cu-Ni+Ge+Bi). This new alloy has an addition that enables thermally stable solder joints even after thermal cycling. Unlike silver-containing alloys that derive their strength from a dispersion of fine particles of eutectic Ag₃Sn, SN100CV gains its strength from solute atoms in the tin matrix of the joint. The unique ability of SN100CV P506 D4 to survive long-term storage at room temperature allows simplification of stock management while meeting all the requirements of modern reflow soldering processes. The SN100CV alloy is also available as a completely halogen-free solder paste, SN100CV P604 D4 and a low residue paste, SN100CV P820-5 D4.



Lead-free Alloy for Soldering Aluminum ALUSAC-35

Despite the cost and the performance advantages of aluminum, its commercial adoption has been slow because of the concern about the galvanic corrosion that results from differences in the

electrical potential of the constituent phases. Joints to aluminum made with this new alloy retain reasonable strength even after 30 days of saltwater immersion.

Alconano Nano-Silver Paste is based on a patented technology that makes it possible to effectively join most metals as well as Si and SiC at low sintering temperatures, if necessary in nitrogen, without the nitrous or sulphurous residues that are the by-products of the sintering of some other nano-silver pastes. The highly active surface of the nano-silver particles and the consequent strong capillary forces make it possible to achieve strong bonds even on copper with high electrical and thermal conductivity at low temperatures without the need for external pressure.



For more information about Nihon Superior's new solder pastes and lead-free products, visit www.nihonsuperior.co.jp/english.

About Nihon Superior Co., Ltd.

Nihon Superior was founded in 1966 when it began marketing unique flux products imported from the US. The company made its mark on society by gathering the most advanced soldering and brazing technologies and products from around the world, and supplying them to companies in the metal-joining industry. A turning point for the company came when it started developing its own soldering materials and with the success of its unique SN100C lead-free solder alloy Nihon Superior has become a major player in the global market. To support the growing demand for its products, Nihon Superior has established manufacturing and sales centers in Japan, China and other Asian countries, and the United States, and formed business partnerships with companies in other markets.

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Planning Sec., Public Relations & Planning Office